

MECHANICAL CASE OUTLINE

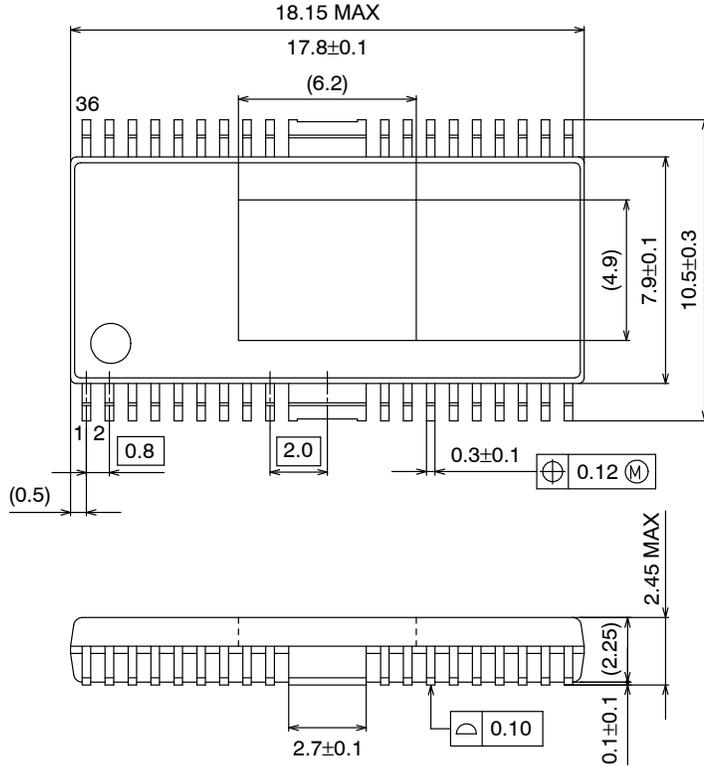
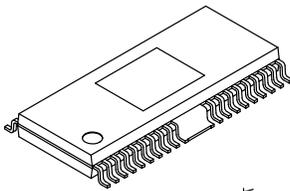
PACKAGE DIMENSIONS

ON Semiconductor®

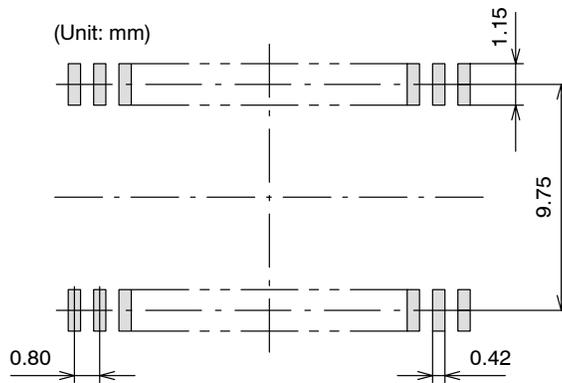


HSOP36R (375mil)
CASE 943AD
ISSUE A

DATE 08 NOV 2013



SOLDERING FOOTPRINT*



NOTES:

1. The measurements are not to guarantee but for reference only.
2. Land pattern design in Fin area to be altered in response to customers' individual application.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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